ABSTRACT

A method of producing an electronic device includes an immobilizing resin layer-forming step that includes forming an immobilizing resin layer on a surface of a support substrate, an electronic part-immobilizing step that includes disposing a plurality of electronic parts on the immobilizing resin layer so that a space is formed between adjacent electronic parts among the plurality of electronic parts to immobilize the plurality of electronic parts on the support substrate via the immobilizing resin layer, a encapsulating material layer-forming step that includes covering the plurality of electronic parts with a encapsulating material to form a encapsulating material layer on the immobilizing resin layer and the plurality of electronic parts, a encapsulating material-curing step that includes curing the encapsulating material by heating the encapsulating material to obtain a encapsulating material cured product which is supported on the support substrate and in which the plurality of electronic parts are disposed, and a removal step that includes removing the encapsulating material cured product supported on the support substrate from the support substrate, the removal step removing the encapsulating material cured product from the support substrate by reducing a molecular weight of a resin included in the immobilizing resin layer. This method ensures that the encapsulating material and the electronic parts are rarely damaged, and a residue can be easily removed when producing a redistribution-type electronic device.